

N - CHANNEL ENHANCEMENT MODE SINGLE FEATURE SIZE™ POWER MOSFET

TARGET DATA

TYPE	V _{DSS}	R _{DS(on)}	I _D
STP16NE06L	60 V	< 0.12 Ω	16 A
STP16NE06LFP	60 V	< 0.12 Ω	11 A

- TYPICAL R_{DS(on)} = 0.09 Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- 175°C OPERATING TEMPERATURE
- HIGH dV/dt CAPABILITY
- APPLICATION ORIENTED CHARACTERIZATION

DESCRIPTION

This Power Mosfet is the latest development of SGS-THOMSON unique "Single Feature Size" process whereby a single body is implanted on a strip layout structure. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

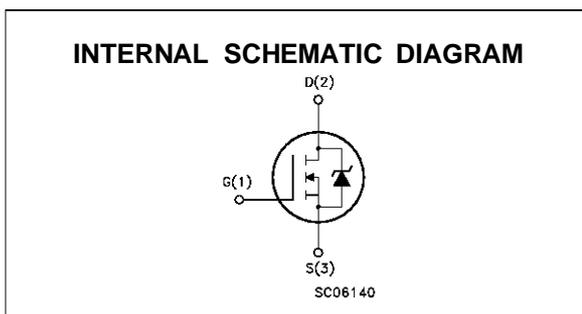
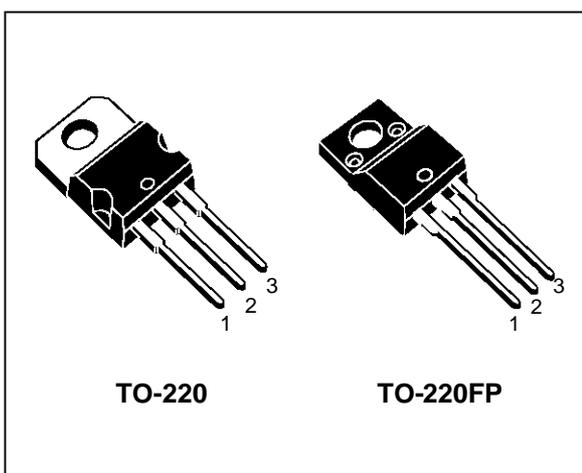
APPLICATIONS

- DC MOTOR CONTROL
- DC-DC & DC-AC CONVERTERS
- SYNCHRONOUS RECTIFICATION

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STP16NE06L	STP16NE06LFP	
V _{DS}	Drain-source Voltage (V _{GS} = 0)	60		V
V _{DGR}	Drain- gate Voltage (R _{GS} = 20 kΩ)	60		V
V _{GS}	Gate-source Voltage	± 15		V
I _D	Drain Current (continuous) at T _c = 25 °C	16	11	A
I _D	Drain Current (continuous) at T _c = 100 °C	10	7	A
I _{DM} (•)	Drain Current (pulsed)	64	64	A
P _{tot}	Total Dissipation at T _c = 25 °C	60	30	W
	Derating Factor	0.4	0.2	W/°C
V _{ISO}	Insulation Withstand Voltage (DC)	—	2000	V
dV/dt	Peak Diode Recovery voltage slope	6		V/ns
T _{stg}	Storage Temperature	-65 to 175		°C
T _j	Max. Operating Junction Temperature	175		°C

(•) Pulse width limited by safe operating area



(1) I_{SD} ≤ 16 A, di/dt ≤ 200 A/μs, V_{DD} ≤ V_{(BR)DSS}, T_j ≤ T_{JMAX}

STP16NE06L/FP

THERMAL DATA

			TO-220	TO-220FP	
R _{thj-case}	Thermal Resistance Junction-case	Max	2.5	5	°C/W
R _{thj-amb}	Thermal Resistance Junction-ambient	Max	62.5		°C/W
R _{thc-sink}	Thermal Resistance Case-sink	Typ	0.5		°C/W
T _l	Maximum Lead Temperature For Soldering Purpose		300		°C

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I _{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T _j max, δ < 1%)	16	A
E _{AS}	Single Pulse Avalanche Energy (starting T _j = 25 °C, I _D = I _{AR} , V _{DD} = 25 V)	80	mJ

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	I _D = 250 μA V _{GS} = 0	60			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = Max Rating V _{DS} = Max Rating T _c = 125 °C			1 10	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 15V			æ 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250 μA	2	3	4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 5V I _D = 8 A V _{GS} = 10V I _D = 8 A		0.090	0.12	Ω
I _{D(on)}	On State Drain Current	V _{DS} > I _{D(on)} × R _{DS(on)max} V _{GS} = 10 V	16			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V _{DS} > I _{D(on)} × R _{DS(on)max} I _D = 8 A		6		S
C _{iss}	Input Capacitance	V _{DS} = 25 V f = 1 MHz V _{GS} = 0		800		pF
C _{oss}	Output Capacitance			100		pF
C _{rss}	Reverse Transfer Capacitance			50		pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Time	$V_{DD} = 30\text{ V}$ $I_D = 8\text{ A}$				ns
t_r	Rise Time	$R_G = 4.7\ \Omega$ $V_{GS} = 5\text{ V}$				ns
Q_g	Total Gate Charge	$V_{DD} = 40\text{ V}$ $I_D = 16\text{ A}$ $V_{GS} = 5\text{ V}$				nC
Q_{gs}	Gate-Source Charge					nC
Q_{gd}	Gate-Drain Charge					nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(Voff)}$	Off-voltage Rise Time	$V_{DD} = 48\text{ V}$ $I_D = 16\text{ A}$				ns
t_f	Fall Time	$R_G = 4.7\ \Omega$ $V_{GS} = 5\text{ V}$				ns
t_c	Cross-over Time					ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain Current					A
$I_{SDM}(\bullet)$	Source-drain Current (pulsed)					A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 16\text{ A}$ $V_{GS} = 0$			1.5	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 16\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 30\text{ V}$ $T_j = 150\text{ }^\circ\text{C}$				ns
Q_{rr}	Reverse Recovery Charge					μC
I_{RRM}	Reverse Recovery Current					A

(*) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %

(\bullet) Pulse width limited by safe operating area